FIG. 1

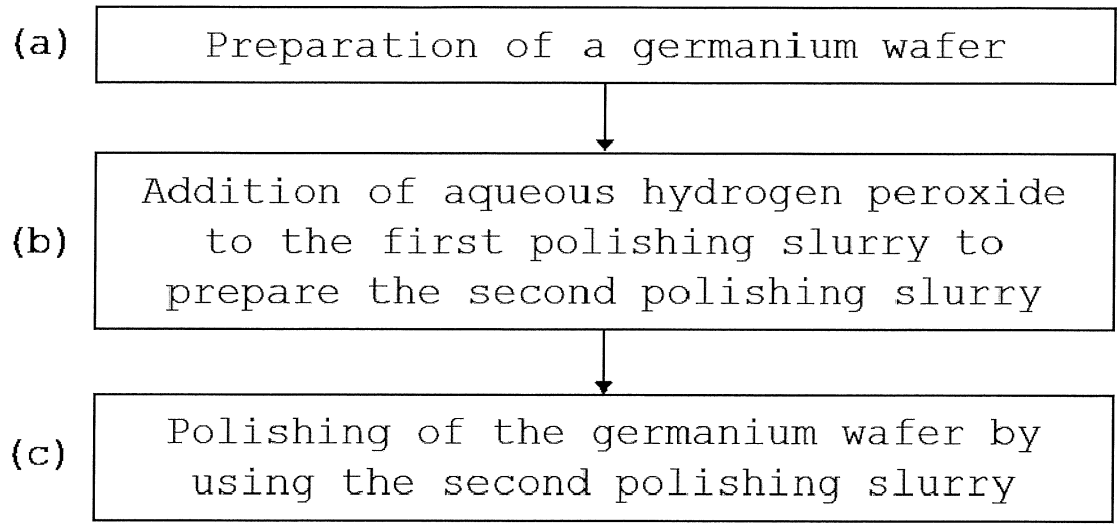

(a)
Preparation of a germanium wafer
(b)
Addition of aqueous hydrogen peroxide to the first polishing slurry to prepare the second polishing slurry
(c)
Polishing of the germanium wafer by using the second polishing slurry

FIG. 2

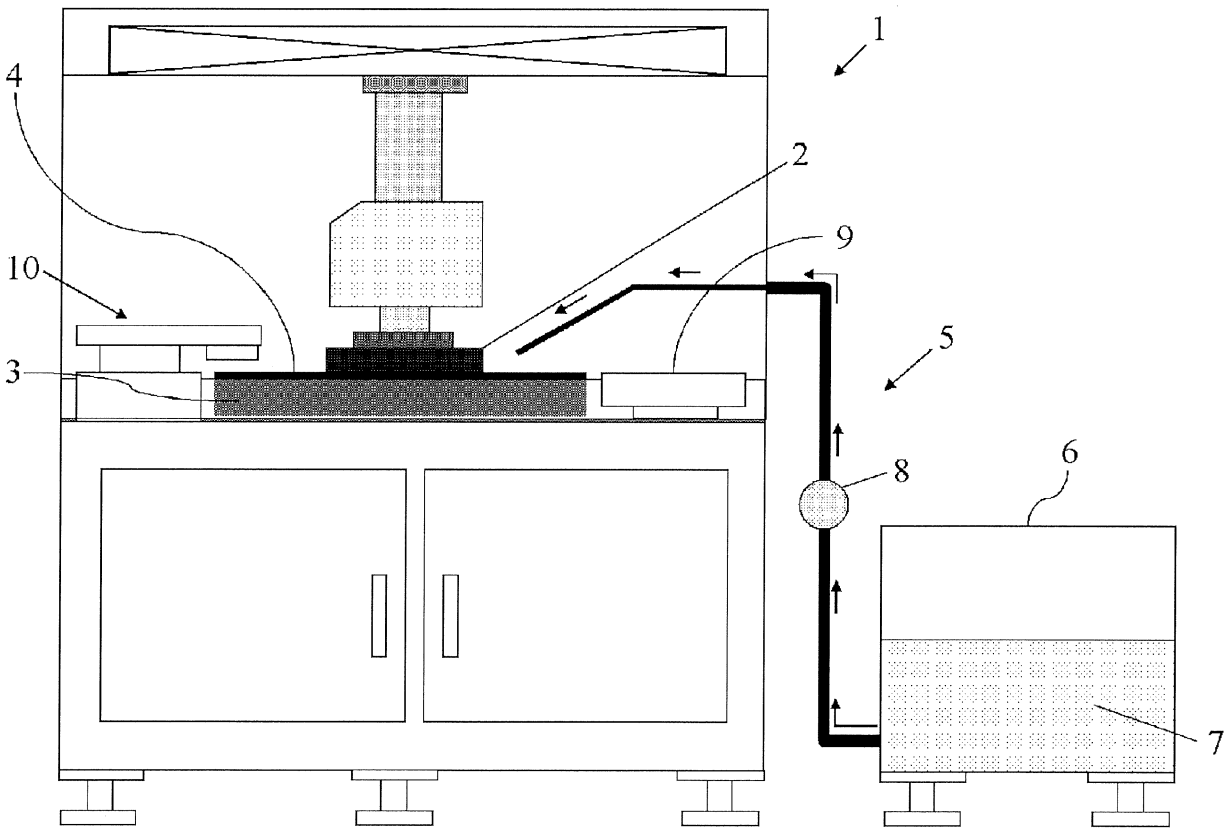
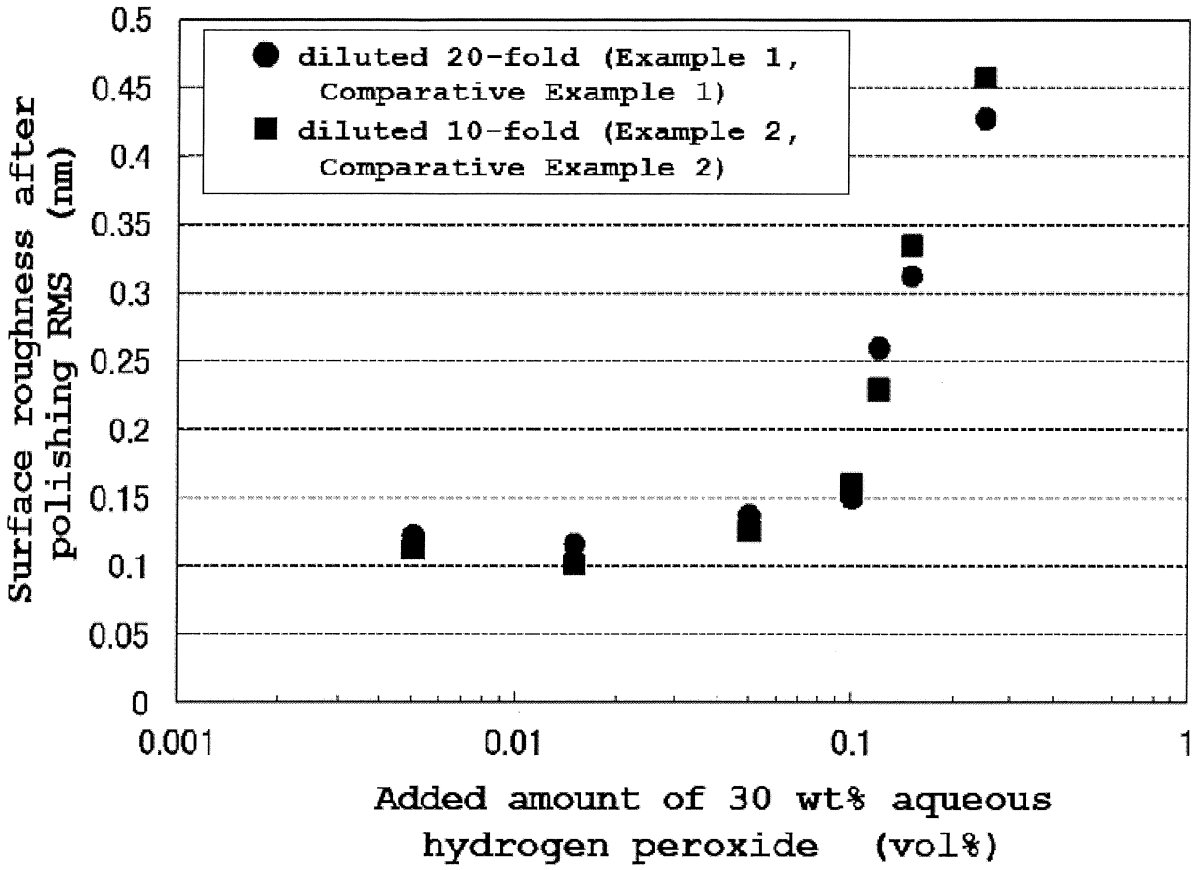

1
2
3
4
5
6
7
8
9
10

FIG. 3


diluted 20-fold (Example 1, Comparative Example 1)
diluted 10-fold (Example 2, Comparative Example 2)
Surface roughness after polishing RMS (nm)
0.5
0.45
0.4
0.35
0.3
0.25
0.2
0.15
0.1
0.05
0
0.001
0.01
0.1
1
Added amount of 30 wt% aqueous hydrogen peroxide (vol%)